

N-Channel Enhancement Mode Power MOSFET

Description

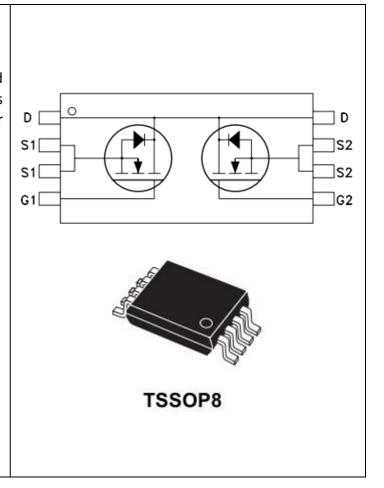
The MS8205A uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

- $V_{DS} = 20V$, $I_D = 5A$ $R_{DS(ON)} < 35mΩ$ @ $V_{GS} = 2.5V$ $R_{DS(ON)} < 30mΩ$ @ $V_{GS} = 4.5V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

- Battery protection
- Load switch
- Power management



Absolute Maximum Ratings (TA=25 ℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V _{GS}	±10	V
Drain Current-Continuous	I _D	5	Α
Drain Current-Pulsed (Note 1)	I _{DM}	25	А
Maximum Power Dissipation	P_{D}	1.5	W
Operating Junction and Storage Temperature Range	T _J ,T _{STG}	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	83	°C/W
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Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	21	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =19.5V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	0.5	0.7	1.2	V
Dunin Course On State Resistance	D	V _{GS} =4.5V, I _D =4.5A	-	23	30	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =2.5V, I _D =3.5A	-	29	35	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V,I _D =4.5A	-	10	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{Iss}		-	600	-	PF
Output Capacitance	C _{oss}	V _{DS} =8V,V _{GS} =0V, F=1.0MHz	-	330	-	PF
Reverse Transfer Capacitance	C _{rss}	. 1.02	-	140	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	10	20	nS
Turn-on Rise Time	t _r		_	11	25	nS
Turn-Off Delay Time	t _{d(off)}	$V_{DD}=10V,I_{D}=1A$	_	35	70	nS
Turn-Off Fall Time	t _f	V_{GS} =4.5 V , R_{GEN} =6 Ω	-	30	60	nS
Total Gate Charge	Qg		-	10	15	nC
Gate-Source Charge	Q_{gs}	$V_{DS}=10V,I_{D}=6A,$	-	2.3	-	nC
Gate-Drain Charge	Q_{gd}	V_{GS} =4.5 V	-	1.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =1.7A	-	0.75	1.2	V
Diode Forward Current (Note 2)	I _S		-	-	1.7	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
- 3. Pulse Test: Pulse Width $\, \leqslant \,$ 300 μ s, Duty Cycle $\, \leqslant \,$ 2%.
- 4. Guaranteed by design, not subject to production



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

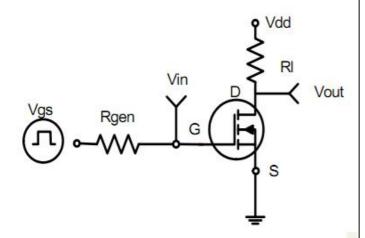


Figure 1:Switching Test Circuit

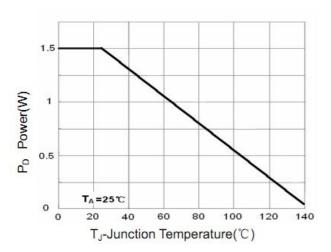


Figure 3 Power Dissipation

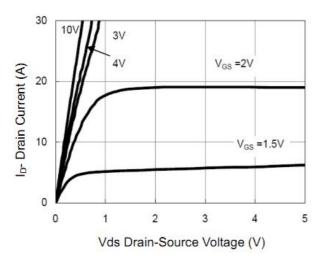


Figure 5 Output CHARACTERISTICS

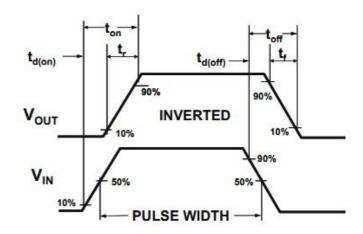


Figure 2:Switching Waveforms

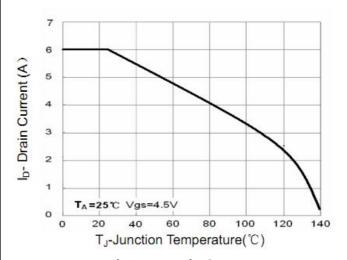


Figure 4 Drain Current

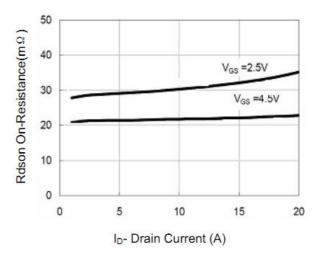


Figure 6 Drain-Source On-Resistance



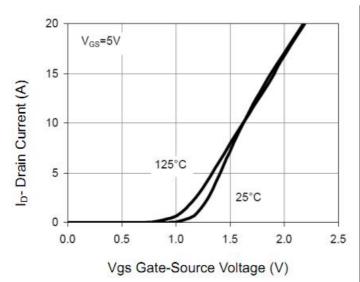
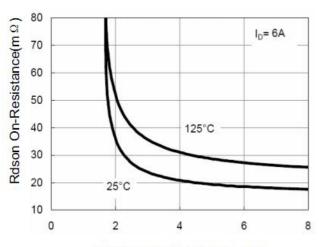


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs

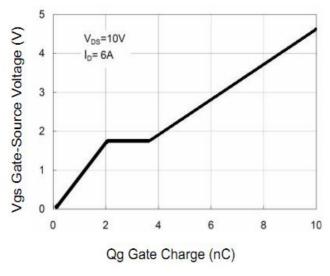


Figure 11 Gate Charge

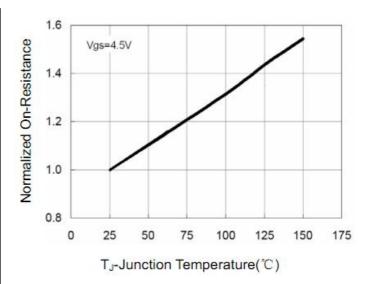


Figure 8 Drain-Source On-Resistance

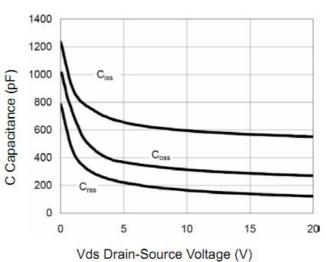


Figure 10 Capacitance vs Vds

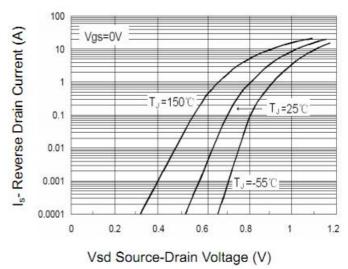


Figure 12 Source- Drain Diode Forward



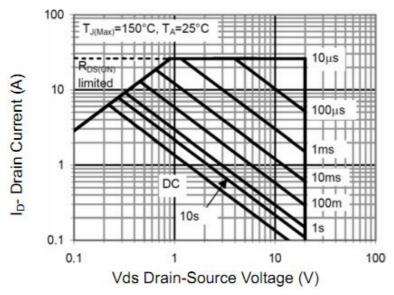


Figure 13 Safe Operation Area

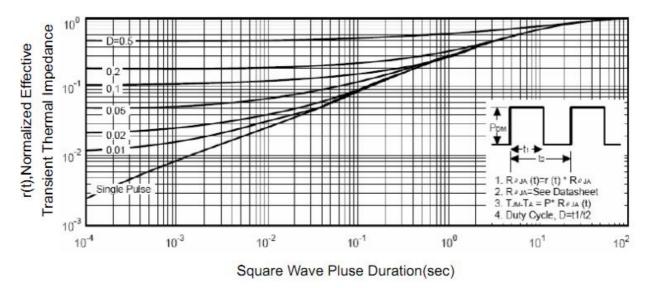
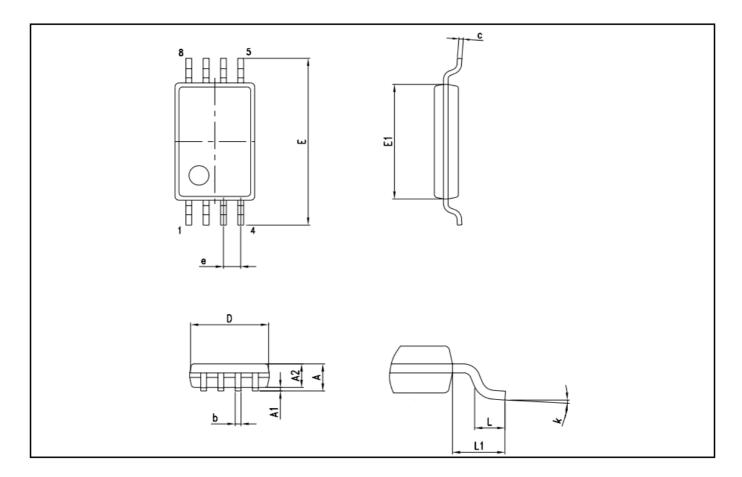


Figure 14 Normalized Maximum Transient Thermal Impedance



TSSOP-8 PACKAGE INFORMATION



DIM.	mm.			inch.			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Α	1.05		1.20	0.041		0.047	
A1	0.05		0.15	0.002		0.006	
A2	0.80		1.05	0.032		0.041	
b	0.19		0.30	0.008		0.012	
С	0.090		0.20	0.003		0.007	
D	2.90		3.10	0.114		0.122	
Е	6.20		6.60	0.240		0.260	
E1	4.30		4.50	0.170		0.177	
е		0.65			0.025		
L	0.45		0.75	0.018		0.030	
L1		1.00			0.039		
k	00		80	0.192		0.208	